

# Qing-An Huang

## List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

227  
papers

2,933  
citations

28  
h-index

46  
g-index

269  
ext. papers

3,620  
ext. citations

3.2  
avg, IF

5.44  
L-index

#	Paper	IF	Citations
227	Analytic Model of Dual-Layer-Structure MEMS Thermal Wind Sensor With Increased Sensitivity. <i>IEEE Transactions on Electron Devices</i> , <b>2022</b> , 1-8	2.9	0
226	Passive and Wireless Anemometer Based on Inductor Bending Effect. <i>Journal of Microelectromechanical Systems</i> , <b>2022</b> , 31, 3-5	2.5	
225	A high-throughput microfluidic diploid yeast long-term culturing (DYLC) chip capable of bud reorientation and concerted daughter dissection for replicative lifespan determination.. <i>Journal of Nanobiotechnology</i> , <b>2022</b> , 20, 171	9.4	1
224	Simulation and experiment of miniaturized housing structure for MEMS thermal wind sensors. <i>Sensors and Actuators A: Physical</i> , <b>2021</b> , 333, 113297	3.9	0
223	Observation of the perturbed eigenvalues of PT-symmetric LC resonator systems. <i>Journal of Physics Communications</i> , <b>2021</b> , 5, 045010	1.2	1
222	Design and 3D modeling investigation of a microfluidic electrode array for electrical impedance measurement of single yeast cells. <i>Electrophoresis</i> , <b>2021</b> , 42, 1996-2009	3.6	2
221	An efficient electro-thermo-mechanical model for the analysis of V-shaped thermal actuator connected with driven structures. <i>International Journal of Numerical Modelling: Electronic Networks, Devices and Fields</i> , <b>2021</b> , 34, e2843	1	0
220	Low-Drift MEMS Thermal Wind Sensor With Symmetric Packaging Using Plastic Injection Molding Process. <i>IEEE Transactions on Instrumentation and Measurement</i> , <b>2021</b> , 70, 1-8	5.2	4
219	Analysis and Compensation of Benchmark Drift of Micromachined Thermal Wind Sensor Caused by Packaging Asymmetry. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 1-1	8.9	4
218	Flexible LC-Type Wind Speed Sensor With Its Readout Circuit. <i>IEEE Sensors Journal</i> , <b>2021</b> , 21, 19857-19862		0
217	Influence of Aerodynamic Housing on the Performance of MEMS Wind Sensor <b>2020</b> ,		1
216	A 2D Waveguide Method for Lithography Simulation of Thick SU-8 Photoresist. <i>Micromachines</i> , <b>2020</b> , 11,	3.3	1
215	Enhancing the Remote Distance of LC Passive Wireless Sensors by Parity-Time Symmetry Breaking. <i>Physical Review Applied</i> , <b>2020</b> , 13,	4.3	4
214	Parallelized Wireless Sensing System for Continuous Monitoring of Microtissue Spheroids. <i>ACS Sensors</i> , <b>2020</b> , 5, 2036-2043	9.2	6
213	An Impedance Matching Method for LC Passive Wireless Sensors. <i>IEEE Sensors Journal</i> , <b>2020</b> , 20, 13833-13841		4
212	Quadruple sensitivity improvement for wind speed sensor using dual-layer bended inductors. <i>Sensors and Actuators A: Physical</i> , <b>2020</b> , 303, 111786	3.9	2
211	An efficient macro model for CMOS-MEMS thermal wind speed sensor. <i>Journal of Micromechanics and Microengineering</i> , <b>2020</b> , 30, 125001	2	1

210	Differential piezoresistive wind speed sensor on flexible substrate. <i>Electronics Letters</i> , <b>2020</b> , 56, 201-203.	1.1	3
209	Uncertainty quantification of MEMS devices with correlated random parameters. <i>Microsystem Technologies</i> , <b>2020</b> , 26, 1689-1696	1.7	0
208	Ceramic Film Packaging for 2-D Thermal Wind Sensor Using LTCC Technology. <i>Journal of Microelectromechanical Systems</i> , <b>2019</b> , 28, 1080-1087	2.5	4
207	Temperature Effect and Its Compensation of a Micromachined 2-D Anemometer. <i>IEEE Sensors Journal</i> , <b>2019</b> , 19, 5454-5459	4	4
206	Modeling of Packaged MEMS Thermal Wind Sensor Operating on CP Mode. <i>IEEE Transactions on Electron Devices</i> , <b>2019</b> , 66, 2375-2381	2.9	2
205	A monolithic integrated ultra-flexible all-solid-state supercapacitor based on a polyaniline conducting polymer. <i>Journal of Materials Chemistry A</i> , <b>2019</b> , 7, 15378-15386	13	19
204	Fabrication of a Piezoresistive Barometric Pressure Sensor by a Silicon-on-Nothing Technology. <i>Journal of Sensors</i> , <b>2019</b> , 2019, 1-10	2	3
203	Modeling, Simulation, and Fabrication of a 2-D Anemometer Based on a Temperature-Balanced Mode. <i>IEEE Sensors Journal</i> , <b>2019</b> , 19, 4796-4803	4	3
202	Novel Anemometer Based on Inductor Bending Effect. <i>Journal of Microelectromechanical Systems</i> , <b>2019</b> , 28, 321-323	2.5	5
201	Low Cost Paper-Based LC Wireless Humidity Sensors and Distance-Insensitive Readout System. <i>IEEE Sensors Journal</i> , <b>2019</b> , 19, 4717-4725	4	22
200	Symmetric LC Circuit Configurations for Passive Wireless Multifunctional Sensors. <i>Journal of Microelectromechanical Systems</i> , <b>2019</b> , 28, 344-350	2.5	7
199	Temperature Effects of a Ceramic MEMS Thermal Wind Sensor Based on a Temperature-Balanced Mode. <i>IEEE Sensors Journal</i> , <b>2019</b> , 19, 7254-7260	4	4
198	Metal oxide semiconductor nanomembrane-based soft unnoticeable multifunctional electronics for wearable human-machine interfaces. <i>Science Advances</i> , <b>2019</b> , 5, eaav9653	14.3	136
197	. <i>IEEE Sensors Journal</i> , <b>2019</b> , 19, 11007-11013	4	4
196	Sensitivity Improvement of MEMS Thermal Wind Sensor Using Vertical Stacking Thermistors <b>2019</b> ,		4
195	A Novel Measurement Method of Mechanical Properties for Individual Layers in Multilayered Thin Films. <i>Micromachines</i> , <b>2019</b> , 10,	3.3	3
194	A Fast Response Flexible Humidity Sensor based on PTFE Micropore Substrate <b>2019</b> ,		1
193	Experiments and Solution of Asymmetry Effect for Mems Thermal wind Sensor <b>2019</b> ,		2

192	. <i>IEEE Sensors Journal</i> , <b>2019</b> , 19, 304-310	4	4
191	Configuration of a Self-Heated Double Wheatstone Bridge for 2-D Wind Sensors. <i>Journal of Microelectromechanical Systems</i> , <b>2019</b> , 28, 125-130	2.5	7
190	Modeling and Simulation of SU-8 Thick Photoresist Lithography. <i>Micro/Nano Technologies</i> , <b>2018</b> , 67-97		
189	RF MEMS Switch. <i>Micro/Nano Technologies</i> , <b>2018</b> , 1039-1076		1
188	Effects of Metal Plane in LC Passive Wireless Sensors <b>2018</b> , 2, 1-3		6
187	Applying Metamaterial-Based Repeater in LC Passive Wireless Sensors to Enhance Readout. <i>IEEE Sensors Journal</i> , <b>2018</b> , 18, 1755-1760	4	6
186	A 2D Wind Sensor Using the $\Delta P$ Thermal Feedback Control. <i>Journal of Microelectromechanical Systems</i> , <b>2018</b> , 27, 377-379	2.5	12
185	Eight-trigram-inspired MEMS thermal wind sensor with improved accuracy <b>2018</b> ,		1
184	Experimental Study of the Bending Effect on LC Wireless Humidity Sensors Fabricated on Flexible PET Substrates. <i>Journal of Microelectromechanical Systems</i> , <b>2018</b> , 27, 761-763	2.5	8
183	High-Voltage Flexible Microsupercapacitors Based on Laser-Induced Graphene. <i>ACS Applied Materials &amp; Interfaces</i> , <b>2018</b> , 10, 26357-26364	9.5	49
182	LC Wireless Sensitive Pressure Sensors With Microstructured PDMS Dielectric Layers for Wound Monitoring. <i>IEEE Sensors Journal</i> , <b>2018</b> , 18, 4886-4892	4	35
181	Modeling and Simulation of Silicon Anisotropic Etching. <i>Micro/Nano Technologies</i> , <b>2018</b> , 3-25		
180	Online Test Microstructures of the Thermophysical Properties of MEMS Conducting Films. <i>Micro/Nano Technologies</i> , <b>2018</b> , 237-302		
179	Online Test Microstructures of the Mechanical Properties for Micromachined Multilayered Films. <i>Micro/Nano Technologies</i> , <b>2018</b> , 197-235		
178	A Micromachined Thermal Wind Sensor. <i>Micro/Nano Technologies</i> , <b>2018</b> , 539-576		1
177	Micromachined Humidity Sensors. <i>Micro/Nano Technologies</i> , <b>2018</b> , 787-816		1
176	Experimental Study of a Dual-Mode Control MEMS Wind Sensor with High Accuracy <b>2018</b> ,		1
175	Flexible Passive Wireless Pressure and Moisture Dual-Parameter Sensor for Wound Monitoring <b>2018</b> ,		2

174	Sensitivity Analysis of Micromachined Thermal Wind Sensor Based on Back Surface Sensing Mode <b>2018,</b>		2
173	Three-Dimensional Simulation of DRIE Process Based on the Narrow Band Level Set and Monte Carlo Method. <i>Micromachines</i> , <b>2018</b> , 9,	3.3	5
172	Annular-Encapsulation Packaging to Realize High-Performance MEMS Thermal Wind Sensor <b>2018,</b>		1
171	Comprehensive Simulations for Ultraviolet Lithography Process of Thick SU-8 Photoresist. <i>Micromachines</i> , <b>2018</b> , 9,	3.3	7
170	Encapsulation glue Effect of Encapsulation Glue on Micromachined Thermal Wind Sensor <b>2018</b> , 2, 1-3		4
169	Readout Distance Enhancement of the Passive Wireless Multi-Parameter Sensing System Using a Repeater Coil. <i>Journal of Sensors</i> , <b>2018</b> , 2018, 1-6	2	
168	Octagon-Shaped 2-D Micromachined Thermal Wind Sensor for High-Accurate Applications. <i>Journal of Microelectromechanical Systems</i> , <b>2018</b> , 27, 739-747	2.5	14
167	DRIE trenches and full-bridges design for sensitivity improvement of MEMS silicon thermal wind sensor <b>2017,</b>		4
166	Experiment of the MEMS Wind Sensor Based on Temperature-Balanced Mode. <i>IEEE Sensors Journal</i> , <b>2017</b> , 17, 2316-2317	4	9
165	Effect of Insulation Trenches on Micromachined Silicon Thermal Wind Sensors. <i>IEEE Sensors Journal</i> , <b>2017</b> , 17, 8324-8331	4	9
164	On-line Test Microstructures of the Mechanical Properties for Micromachined Multilayered Films. <i>Toxinology</i> , <b>2017</b> , 1-40	0	
163	A Generalized Polynomial Chaos-Based Approach to Analyze the Impacts of Process Deviations on MEMS Beams. <i>Sensors</i> , <b>2017</b> , 17,	3.8	4
162	Modeling and Simulation of SU-8 Thick Photoresist Lithography. <i>Toxinology</i> , <b>2017</b> , 1-31	0	1
161	Online Test Microstructures of the Thermophysical Properties of MEMS Conducting Films. <i>Toxinology</i> , <b>2017</b> , 1-67	0	
160	Effects of environmental media on the transmission of an inductive link in wireless microsystems. <i>Frontiers of Mechanical Engineering</i> , <b>2017</b> , 12, 554-556	3.3	1
159	RF MEMS Switch. <i>Toxinology</i> , <b>2017</b> , 1-38	0	
158	Modelling and characterization of a robust, low-power and wide-range thermal wind sensor. <i>Microsystem Technologies</i> , <b>2017</b> , 23, 5571-5585	1.7	4
157	. <i>Journal of Microelectromechanical Systems</i> , <b>2017</b> , 26, 1073-1081	2.5	31

156	A Micro-Test Structure for the Thermal Expansion Coefficient of Metal Materials. <i>Micromachines</i> , <b>2017</b> , 8, 70	3.3	1
155	Modeling of the Effect of Process Variations on a Micromachined Doubly-Clamped Beam. <i>Micromachines</i> , <b>2017</b> , 8, 81	3.3	3
154	A Simple Extraction Method of Young's Modulus for Multilayer Films in MEMS Applications. <i>Micromachines</i> , <b>2017</b> , 8,	3.3	7
153	Micromachined Humidity Sensors. <i>Toxinology</i> , <b>2017</b> , 1-30	0	1
152	A Micromachined Thermal Wind Sensor. <i>Toxinology</i> , <b>2017</b> , 1-43	0	
151	Modeling and Simulation of Silicon Anisotropic Etching. <i>Toxinology</i> , <b>2017</b> , 1-23	0	
150	A robust and low-power 2-D thermal wind sensor based on a glass-in-silicon reflow process. <i>Microsystem Technologies</i> , <b>2016</b> , 22, 151-162	1.7	5
149	. <i>IEEE Transactions on Circuits and Systems I: Regular Papers</i> , <b>2016</b> , 63, 1426-1433	3.9	10
148	A Passive Wireless Adaptive Repeater for Enhancing the Readout of LC Passive Wireless Sensors. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2016</b> , 26, 543-545	2.6	26
147	A New Method for Real-Time Measuring the Temperature-Dependent Dielectric Constant of the Silicone Oil. <i>IEEE Sensors Journal</i> , <b>2016</b> , 16, 8792-8797	4	4
146	Sensitivity Improvement of a 2D MEMS Thermal Wind Sensor for Low-Power Applications. <i>IEEE Sensors Journal</i> , <b>2016</b> , 16, 4300-4308	4	19
145	In-Situ Testing of the Thermal Diffusivity of Polysilicon Thin Films. <i>Micromachines</i> , <b>2016</b> , 7,	3.3	1
144	Passive Wireless Hermetic Environment Monitoring System for Spray Painting Workshop. <i>Sensors</i> , <b>2016</b> , 16,	3.8	4
143	Parallel capacitive temperature micro-sensor for passive wireless sensing applications. <i>Electronics Letters</i> , <b>2016</b> , 52, 1345-1347	1.1	2
142	An LC Passive Wireless Multifunctional Sensor Using a Relay Switch. <i>IEEE Sensors Journal</i> , <b>2016</b> , 16, 4968-4973	4	12
141	LC Passive Wireless Sensors Toward a Wireless Sensing Platform: Status, Prospects, and Challenges. <i>Journal of Microelectromechanical Systems</i> , <b>2016</b> , 25, 822-841	2.5	123
140	. <i>Journal of Microelectromechanical Systems</i> , <b>2015</b> , 24, 1117-1123	2.5	54
139	Laterally-actuated inside-driven RF MEMS switches fabricated by a SOG process. <i>Journal of Micromechanics and Microengineering</i> , <b>2015</b> , 25, 065007	2	7

138	Implementation of Multiparameter Monitoring by an LC-Type Passive Wireless Sensor Through Specific Winding Stacked Inductors. <i>IEEE Internet of Things Journal</i> , <b>2015</b> , 2, 168-174	10.7	29
137	Development of a self-packaged 2D MEMS thermal wind sensor for low power applications. <i>Journal of Micromechanics and Microengineering</i> , <b>2015</b> , 25, 085011	2	21
136	. <i>Journal of Microelectromechanical Systems</i> , <b>2015</b> , 24, 2033-2039	2.5	13
135	Development of a robust 2-D thermal wind sensor using glass reflow process for low power applications <b>2015</b> ,		2
134	A self-packaged self-heated thermal wind sensor with high reliability and low power consumption <b>2015</b> ,		1
133	Effects of thermally induced packaging stress on a distributed RF MEMS phase shifter. <i>Microsystem Technologies</i> , <b>2015</b> , 21, 869-874	1.7	2
132	Temperature Effects on the Wind Direction Measurement of 2D Solid Thermal Wind Sensors. <i>Sensors</i> , <b>2015</b> , 15, 29871-81	3.8	6
131	. <i>Journal of Microelectromechanical Systems</i> , <b>2015</b> , 24, 575-581	2.5	57
130	Three-dimensional simulation of surface topography evolution in the Bosch process by a level set method. <i>Microsystem Technologies</i> , <b>2015</b> , 21, 1587-1593	1.7	1
129	Temperature dependence of the quality factor in LC-type passive wireless temperature sensors <b>2015</b> ,		1
128	Effects of Ambient Humidity on a Micromachined Silicon Thermal Wind Sensor. <i>Journal of Microelectromechanical Systems</i> , <b>2014</b> , 23, 253-255	2.5	7
127	In-situ determination of the coefficient of thermal expansion of polysilicon thin films using micro-rotating structures. <i>Thin Solid Films</i> , <b>2014</b> , 552, 184-191	2.2	5
126	Novel DC-40 GHz MEMS series-shunt switch for high isolation and high power applications. <i>Sensors and Actuators A: Physical</i> , <b>2014</b> , 214, 101-110	3.9	17
125	2-D Micromachined Thermal Wind Sensors A Review. <i>IEEE Internet of Things Journal</i> , <b>2014</b> , 1, 216-232	10.7	64
124	A simple method for extracting material parameters of multilayered MEMS structures using resonance frequency measurements. <i>Journal of Micromechanics and Microengineering</i> , <b>2014</b> , 24, 075014 <sup>2</sup>		8
123	A passive wireless integrated humidity sensor based on dual-layer spiral inductors <b>2014</b> ,		1
122	A self-packaged two-dimensional thermal wind sensor based on thermopiles for low cost applications. <i>Journal of Micromechanics and Microengineering</i> , <b>2014</b> , 24, 075008	2	3
121	Passive wireless integrated humidity sensor based on dual-layer spiral inductors. <i>Electronics Letters</i> , <b>2014</b> , 50, 1287-1289	1.1	30

120	Large scale three-dimensional simulations for thick SU-8 lithography process based on a full hash fast marching method. <i>Microelectronic Engineering</i> , <b>2014</b> , 123, 171-174	2.5	4
119	Temperature sensing properties of the passive wireless sensor based on graphene oxide films <b>2014</b> ,		4
118	A novel capacitive temperature sensor for a lab-on-a-chip system <b>2014</b> ,		3
117	Extending the remote distance of LC passive wireless sensors via strongly coupled magnetic resonances. <i>Journal of Micromechanics and Microengineering</i> , <b>2014</b> , 24, 125021	2	36
116	Design of LC-type passive wireless multi-parameter sensor <b>2013</b> ,		6
115	Effect of Environmental Humidity on Dielectric Charging Effect in RF MEMS Capacitive Switches Based on $\text{Si}_3\text{N}_4$ Properties. <i>Journal of Microelectromechanical Systems</i> , <b>2013</b> , 22, 637-645	2.5	15
114	MEMS-Based Intraoperative Monitoring System for Improved Safety in Lumbar Surgery. <i>IEEE Sensors Journal</i> , <b>2013</b> , 13, 1541-1548	4	2
113	Lateral Contact Three-State RF MEMS Switch for Ground Wireless Communication by Actuating Rhombic Structures. <i>Journal of Microelectromechanical Systems</i> , <b>2013</b> , 22, 10-12	2.5	16
112	A Novel Three-State RF MEMS Switch for Ultrabroadband (DC-40 GHz) Applications. <i>IEEE Electron Device Letters</i> , <b>2013</b> , 34, 1062-1064	4.4	26
111	H <sub>2</sub> O adsorption-induced curvature of a silicon nanocantilever based on a semi-continuum method. <i>Applied Surface Science</i> , <b>2013</b> , 282, 662-671	6.7	3
110	System-Level Modeling of Packaging Effects of MEMS Devices. <i>Advanced Micro &amp; Nanosystems</i> , <b>2013</b> , 147-161		1
109	In situtest structures for the thermal expansion coefficient and residual stress of polysilicon thin films. <i>Journal of Micromechanics and Microengineering</i> , <b>2013</b> , 23, 075019	2	2
108	Gamma and electron beam irradiation effects on the resistance of micromachined polycrystalline silicon beams. <i>Sensors and Actuators A: Physical</i> , <b>2012</b> , 177, 99-104	3.9	15
107	Fabrication of a Micromachined Two-Dimensional Wind Sensor by Au/Au Wafer Bonding Technology. <i>Journal of Microelectromechanical Systems</i> , <b>2012</b> , 21, 467-475	2.5	47
106	Fabrication of a push-pull type electrostatic comb-drive RF MEMS switch <b>2012</b> ,		2
105	An equivalent-circuit method for coupled-field modeling of distributed RF MEMS devices and packages <b>2012</b> ,		1
104	Direct observation of blocked nanoscale surface evaporation on SiO <sub>2</sub> nanodroplets. <i>Applied Physics Letters</i> , <b>2012</b> , 101, 183114	3.4	1
103	Modeling of silicon thermal expansion using strained phonon spectra. <i>Journal of Micromechanics and Microengineering</i> , <b>2012</b> , 22, 085007	2	4



102	Fullerene as electrical hinge. <i>Applied Physics Letters</i> , <b>2012</b> , 100, 193111	3.4	6
101	A memory and computation efficient three-dimensional simulation system for the UV lithography of thick SU-8 photoresists <b>2012</b> ,		1
100	Measurement of material properties for polysilicon thin films by an electrostatic force method <b>2012</b> ,		1
99	Micro-rotating structures for determining thermal expansion coefficients of polysilicon thin films <b>2012</b> ,		2
98	An online test structure for the thermal expansion coefficient of surface micromachined polysilicon beams by a pull-in approach. <i>Journal of Micromechanics and Microengineering</i> , <b>2012</b> , 22, 055017	2	3
97	A Fully Packaged CMOS Interdigital Capacitive Humidity Sensor With Polysilicon Heaters. <i>IEEE Sensors Journal</i> , <b>2011</b> , 11, 2986-2992	4	49
96	Enhanced performance of a CMOS interdigital capacitive humidity sensor by graphene oxide <b>2011</b> ,		21
95	An Efficient Simulation System for Inclined UV Lithography Processes of Thick SU-8 Photoresists. <i>IEEE Transactions on Semiconductor Manufacturing</i> , <b>2011</b> , 24, 294-303	2.6	8
94	A MEMS pressure sensor based on Hall effect <b>2011</b> ,		5
93	A hot film wind sensor with four Constant Temperature Difference elements fabricated on ceramic substrate <b>2011</b> ,		7
92	Humidity sensing properties of the sensor based on graphene oxide films with different dispersion concentrations <b>2011</b> ,		9
91	Micromachining of Pyrex 7740 Glass by Silicon Molding and Vacuum Anodic Bonding. <i>Journal of Microelectromechanical Systems</i> , <b>2011</b> , 20, 909-915	2.5	18
90	Modelling of the elastic properties of crystalline silicon using lattice dynamics. <i>Journal Physics D: Applied Physics</i> , <b>2011</b> , 44, 335401	3	9
89	A system level modeling for distributed RF MEMS devices considering thermally induced packaging effect <b>2011</b> ,		1
88	Wafer level packaging based on AU-AU bonding for a CMOS compatible thermal wind sensor <b>2011</b> ,		3
87	Gamma Irradiation Effects on Surface-Micromachined Polysilicon Resonators. <i>Journal of Microelectromechanical Systems</i> , <b>2011</b> , 20, 1071-1073	2.5	10
86	Complementary metal-oxide semiconductor compatible capacitive barometric pressure sensor. <i>Journal of Micro/ Nanolithography, MEMS, and MOEMS</i> , <b>2011</b> , 10, 013018	0.7	1
85	A Modified 3D Fast marching simulation for thick photoresists lithography <b>2011</b> ,		4

84	A hybrid model for the charging process of the amorphous SiO <sub>2</sub> film in radio frequency microelectromechanical system capacitive switches. <i>Chinese Physics B</i> , <b>2011</b> , 20, 037701	1.2	2
83	Detecting magnetic field direction by a micro beam operating in different vibration modes. <i>Chinese Physics B</i> , <b>2011</b> , 20, 097101	1.2	1
82	Animal experimental study on the nerve root retraction with a silicon pressure sensor <b>2011</b> ,		1
81	A micromachined silicon capacitive temperature sensor for wide temperature range applications. <i>Journal of Micromechanics and Microengineering</i> , <b>2010</b> , 20, 055036	2	13
80	A CMOS interdigital capacitive humidity sensor with polysilicon heaters <b>2010</b> ,		1
79	Micromachining of Pyrex7740 glass and their applications to wafer-level hermetic packaging of MEMS devices <b>2010</b> ,		5
78	Hot-forming of micro glass cavities for MEMS wafer level hermetic packaging <b>2010</b> ,		3
77	A Cross-Type Thermal Wind Sensor With Self-Testing Function. <i>IEEE Sensors Journal</i> , <b>2010</b> , 10, 340-346	4	33
76	Strain Effect of the Dielectric Constant in Silicon Dioxide. <i>Journal of Microelectromechanical Systems</i> , <b>2010</b> , 19, 1521-1523	2.5	4
75	A FCOB packaged thermal wind sensor with compensation. <i>Microsystem Technologies</i> , <b>2010</b> , 16, 511-518	1.7	24
74	A 3D profile simulator for inclined/multi-directional UV lithography process of negative-tone thick photoresists <b>2009</b> ,		4
73	Orientation Effects in Ballistic High-Strained P-type Si Nanowire FETs. <i>Sensors</i> , <b>2009</b> , 9, 2746-59	3.8	9
72	Modeling and Simulations of Anisotropic Etching of Silicon in Alkaline Solutions with Experimental Verification. <i>Journal of the Electrochemical Society</i> , <b>2009</b> , 156, F29	3.9	17
71	A nodal analysis model for the out-of-plane beamshape electrothermal microactuator. <i>Microsystem Technologies</i> , <b>2009</b> , 15, 217-225	1.7	4
70	A system-level model for a silicon thermal flow sensor. <i>Microsystem Technologies</i> , <b>2009</b> , 15, 279-285	1.7	10
69	Influence of environmental temperature on the dynamic properties of a die attached MEMS device. <i>Microsystem Technologies</i> , <b>2009</b> , 15, 925-932	1.7	10
68	A nodal analysis method for electromechanical behavior simulation of bow-tie shaped microbeams. <i>Microsystem Technologies</i> , <b>2009</b> , 15, 985-991	1.7	7
67	Pull-in characterization of doubly-clamped composite beams. <i>Sensors and Actuators A: Physical</i> , <b>2009</b> , 151, 118-126	3.9	17

66	Modeling of H <sub>2</sub> O adsorption-induced curvature of a metal/silicon nanocantilever. <i>Applied Surface Science</i> , <b>2009</b> , 255, 9404-9408	6.7	7
65	The influence of surface effects on size-dependent mechanical properties of silicon nanobeams at finite temperature. <i>Journal Physics D: Applied Physics</i> , <b>2009</b> , 42, 045409	3	17
64	A Micromachined Inline-Type Wideband Microwave Power Sensor Based on GaAs MMIC Technology. <i>Journal of Microelectromechanical Systems</i> , <b>2009</b> , 18, 705-714	2.5	41
63	. <i>Journal of Microelectromechanical Systems</i> , <b>2009</b> , 18, 274-286	2.5	21
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